

Title (en)

METAL AND ELECTRONIC DEVICE COATING PROCESS FOR MARINE USE AND OTHER ENVIRONMENTS

Title (de)

BESCHICHTUNGSVERFAHREN FÜR METALLE UND ELEKTRONISCHE GERÄTE ZUR ANWENDUNG AUF SEE UND IN ÄHNLICHEN UMGEBUNGEN

Title (fr)

PROCÉDÉ DE REVÊTEMENT DE MÉTAUX ET DE DISPOSITIFS ÉLECTRONIQUES À USAGE MARITIME ET AUTRE ENVIRONNEMENTS

Publication

EP 2328692 A2 20110608 (EN)

Application

EP 09762789 A 20090305

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Abstract (en)

[origin: WO2009151492A2] The present disclosure relates, in part, to Parylene based conformal coating compositions having improved properties, e.g., improved heat transfer and durability characteristics, as well as a methods and apparatus to coat objects with these compositions, and objects coated with these compositions. In some aspects, coating compositions comprising Parylene and boron nitride are disclosed. The disclosure also includes objects (e.g., electronic equipment, textiles, etc.) having a conformal coating comprising a Parylene compound and boron nitride.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

See references of WO 2009151492A2

Citation (examination)

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- US 7064439 B1 20060620 - BERTHOLD JOERG [DE], et al
- KR 20080088966 A 20081006 - HYNIX SEMICONDUCTOR INC [KR]

Designated contracting state (EPC)

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